

PCN Number:	20171005001	PCN Date:	October 09, 2017
Title:	Datasheet for INA231		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc. The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



INA231

SBOS644B – FEBRUARY 2013 – REVISED AUGUST 2017

Changes from Revision A (June 2017) to Revision B

Page

• Changed NC pin description from "No internal connection" to "Do not connect, leave floating"	3
• Changed SCL max value from $V_S + 0.3\text{ V}$ to 6 V in <i>Absolute Maximum Ratings</i> table	4
• Added text to end of <i>Layout Guidelines</i> section clarifying no connection of NC pins	32

Changes from Original (February 2013) to Revision A

Page

• Added <i>Device Information</i> , <i>Recommended Operating Conditions</i> , and <i>ESD Ratings</i> tables, and <i>Detailed Description</i> , <i>Application and Implementation</i> , <i>Power Supply Recommendations</i> , <i>Layout</i> , <i>Device and Documentation Support</i> , and <i>Mechanical, Packaging, and Orderable Information</i> sections	1
• Added new WSCP-12 (YFD) package with 0.4-mm package height and associated content to data sheet	1
• Added operating ambient temperature, T_A to <i>Absolute Maximum Ratings</i> table	4
• Added new note 1 to <i>Timing Requirements: I2C Bus</i> section	6
• Added test condition to Figure 2	7

The datasheet number will be changing.

Device Family	Change From:	Change To:
INA231	SBOS644	SBOS644B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/INA231>

Reason for Change:

To accurately represent the device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

INA231AIYFDR	INA231AIYFDT	INA231AIYFFR	INA231AIYFFT
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com